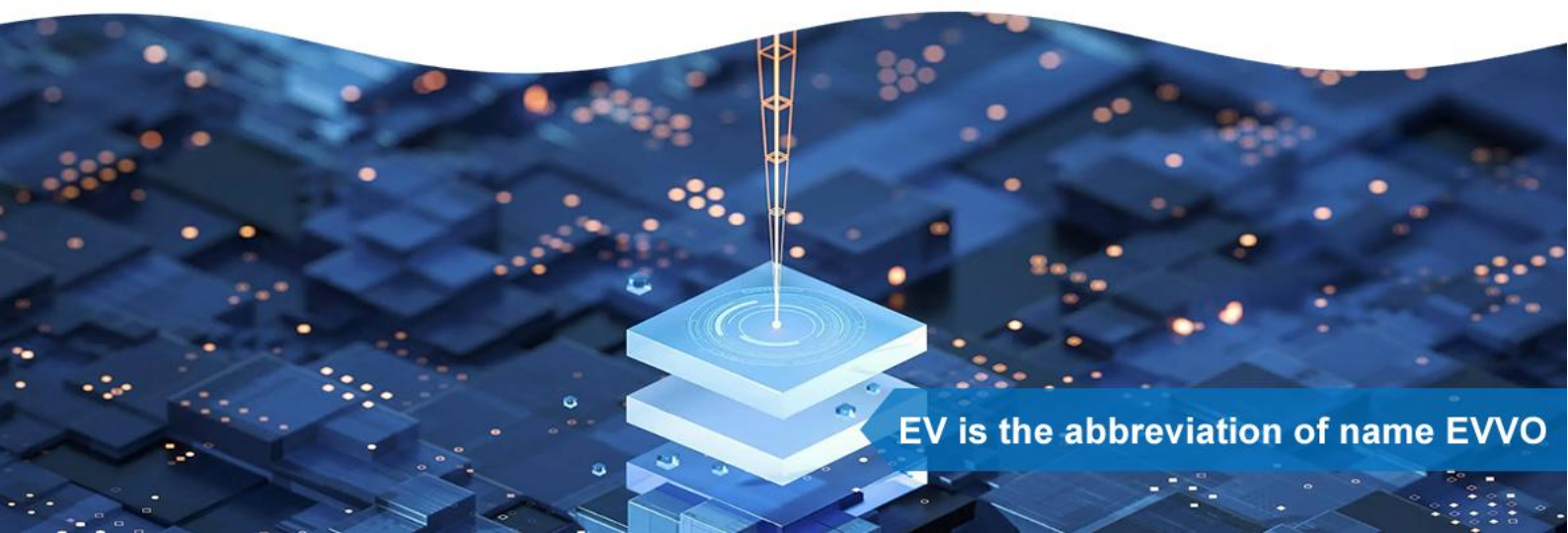
EVVOSEMI®
THINK CHANGE DO

ESD TVS MOS LDO Diode Sensor DC-DC

Product Specification

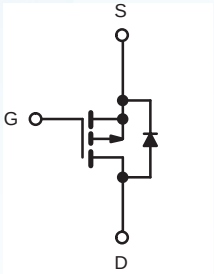
Domestic Part Number	SI4425DY
Overseas Part Number	SI4425DY
Equivalent Part Number	SI4425DY



P-Channel 30 V (D-S) MOSFET

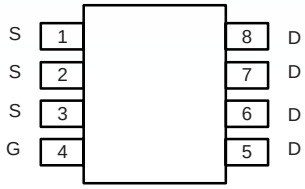
PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (mΩ)	I_D (A)[d]	Q_g (Typ.)
- 30	12.5 at V_{GS} = - 10 V	- 11.6	22 nC
	18 at V_{GS} = - 4.5 V	- 10	



P-Channel MOSFET

SOP-8



Top View

APPLICATIONS

- Load Switches
  - Notebook PCs
  - Desktop PCs

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	- 11.6	A
	T_C = 70 °C		- 10.5	
	T_A = 25 °C		- 8.7[a, b]	
	T_A = 70 °C		- 7.7[a, b]	
Pulsed Drain Current		I_{DM}	- 40	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	- 4.6	
	T_A = 25 °C		2.0[a, b]	
Avalanche Current	L = 0.1 mH	I_{AS}	- 20	
Single-Pulse Avalanche Energy		E_{AS}	20	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	5.6	W
	T_C = 70 °C		3.6	
	T_A = 25 °C		2.5[a, b]	
	T_A = 70 °C		1.6[a, b]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[a, c]	t ≤ 10 s	R_{thJA}	39	50	°C/W
Maximum Junction-to-Foot	Steady State	R_{thJF}	18	22	

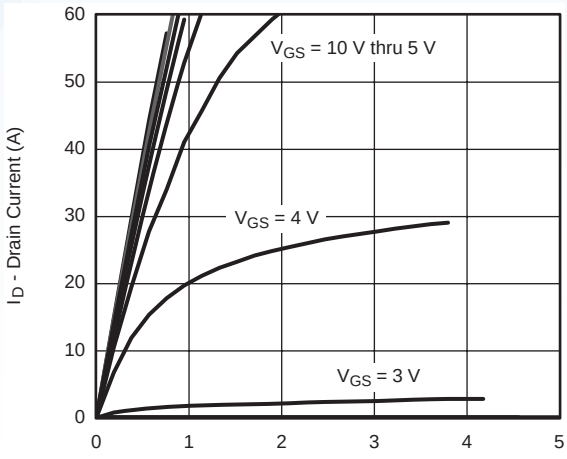
Notes:
a. Surface mounted on 1" x 1" FR4 board.
b. t = 10 s.
c. Maximum under Steady State conditions is 85 °C/W.
d. Based on T_C = 25 °C.

SPECIFICATIONS T_J = 25 °C, unless otherwise noted

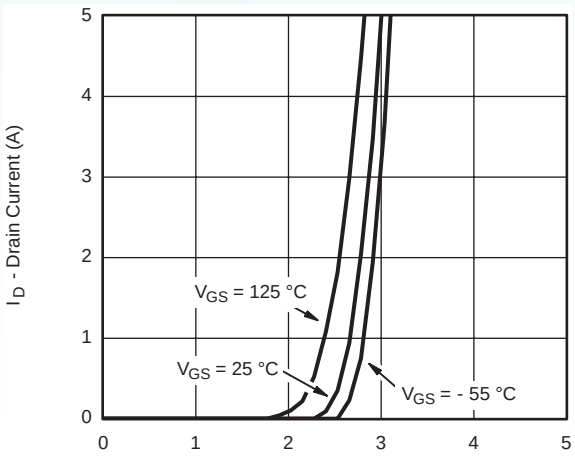
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = - 250 µA	- 30			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = - 250 µA		- 31		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = - 250 µA	- 1.0		- 3.0	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 25 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = - 30 V, V_{GS} = 0 V			- 1	µA
		V_{DS} = - 30 V, V_{GS} = 0 V, T_J = 55 °C			- 5	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ - 10 V, V_{GS} = - 10 V	- 30			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = - 10 V, I_D = - 10 A		11	12.5	mΩ
		V_{GS} = - 4.5 V, I_D = - 7 A		12	18	
Forward Transconductance[a]	g_{fs}	V_{DS} = - 10 V, I_D = - 10 A		23		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = - 15 V, V_{GS} = 0 V, f = 1 MHz		1960		pF
Output Capacitance	C_{oss}			380		
Reverse Transfer Capacitance	C_{rss}			325		
Total Gate Charge	Q_g	V_{DS} = - 15 V, V_{GS} = - 10 V, I_D = - 10 A		43	65	nC
		V_{DS} = - 15 V, V_{GS} = - 4.5 V, I_D = - 10 A		22	33	
Gate-Source Charge	Q_{gs}			6		
Gate-Drain Charge	Q_{gd}			11		
Gate Resistance	R_g	f = 1 MHz	0.3	1.3	2.5	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = - 15 V, R_L = 3 Ω I_D ≅ - 5 A, V_{GEN} = - 10 V, R_g = 1 Ω		11	22	ns
Rise Time	t_r			13	25	
Turn-Off DelayTime	$t_{d(off)}$			32	50	
Fall Time	t_f			9	18	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = - 15 V, R_L = 3 Ω I_D ≅ - 5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		44	70	
Rise Time	t_r			100	160	
Turn-Off DelayTime	$t_{d(off)}$			28	50	
Fall Time	t_f			15	30	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			- 4.6	A
Pulse Diode Forward Current	I_{SM}				- 50	
Body Diode Voltage	V_{SD}	I_S = - 2 A, V_{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = - 2 A, dI/dt = 100 A/µs, T_J = 25 °C		28	45	ns
Body Diode Reverse Recovery Charge	Q_{rr}			20	40	nC
Reverse Recovery Fall Time	t_a			13		ns
Reverse Recovery Rise Time	t_b			15		

Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

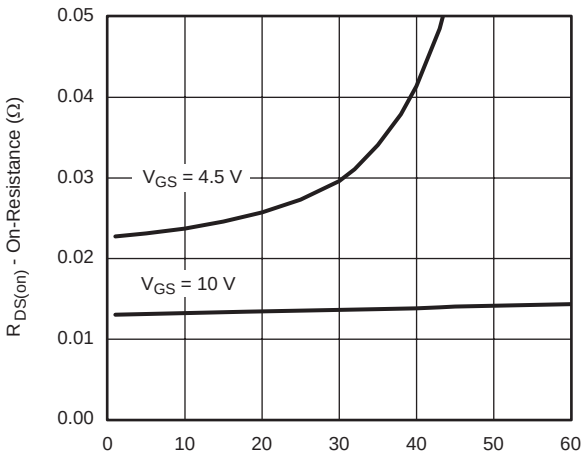
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



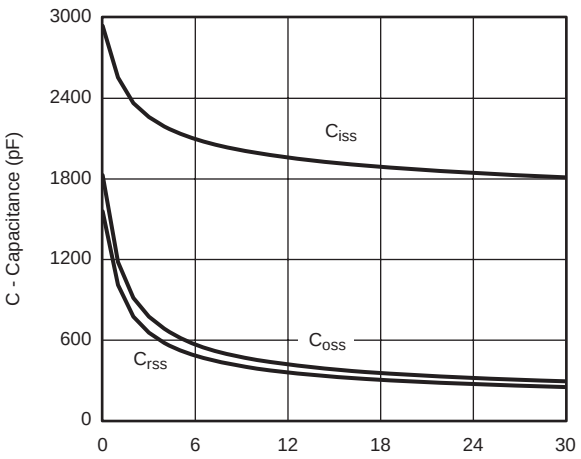
Output Characteristics



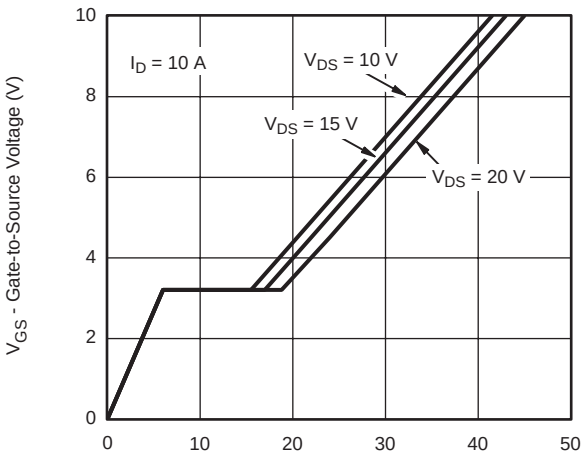
Transfer Characteristics



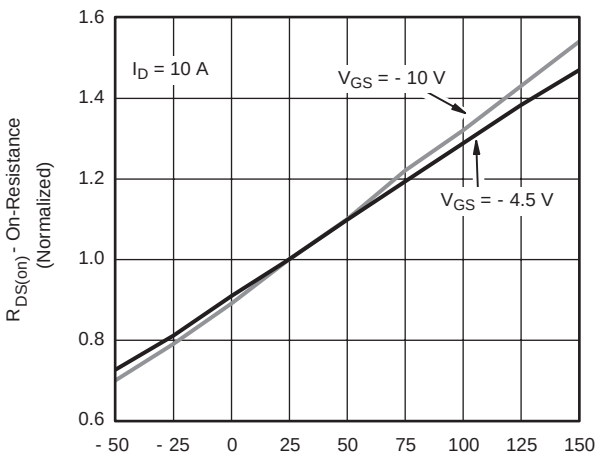
On-Resistance vs. Drain Current



Capacitance

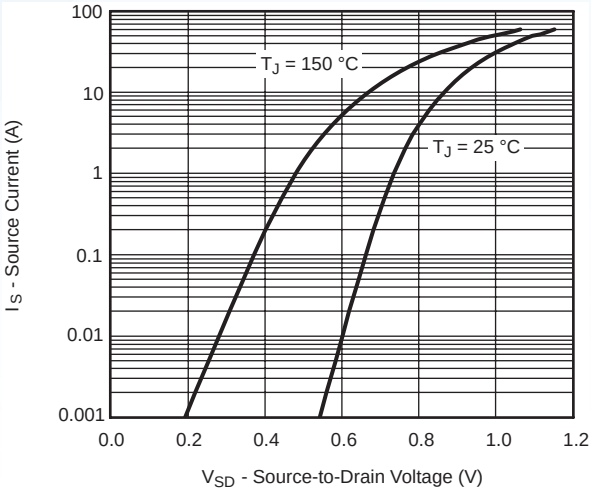


Gate Charge

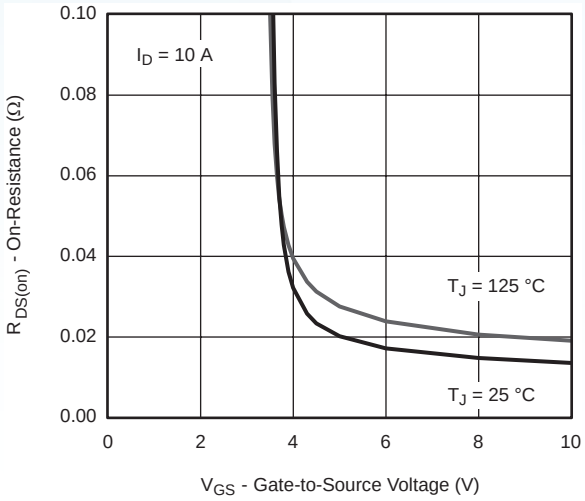


On-Resistance vs. Junction Temperature

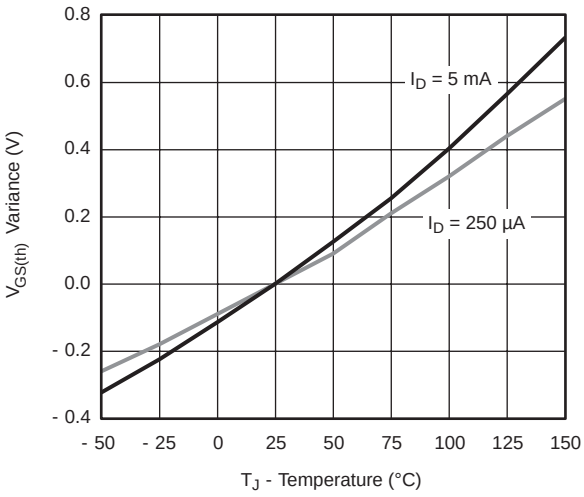
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



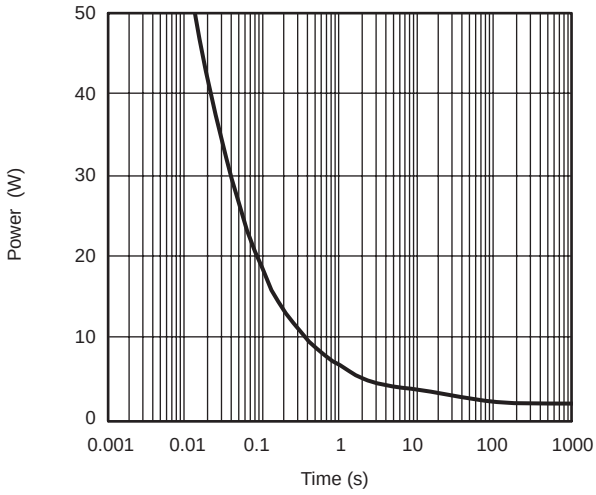
Source-Drain Diode Forward Voltage



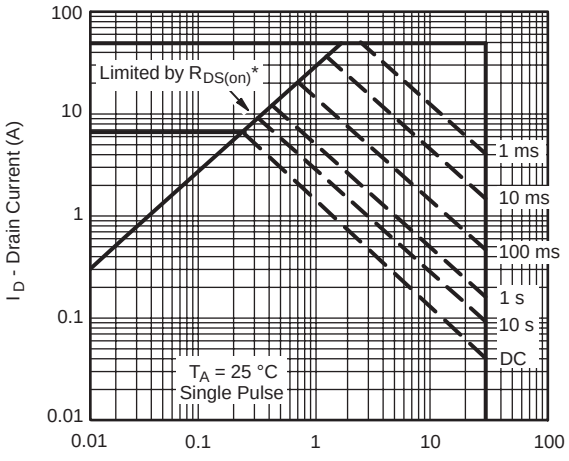
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



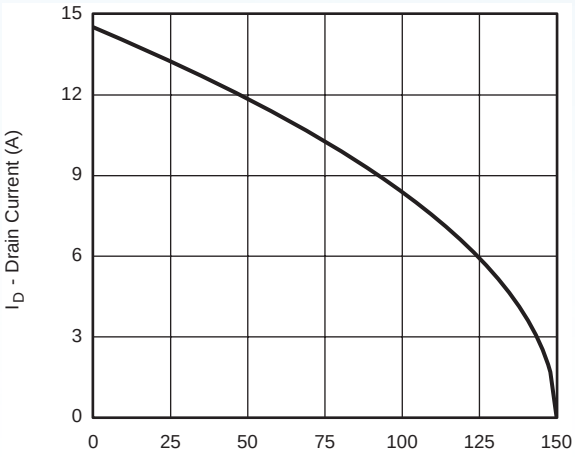
Single Pulse Power, Junction-to-Ambient



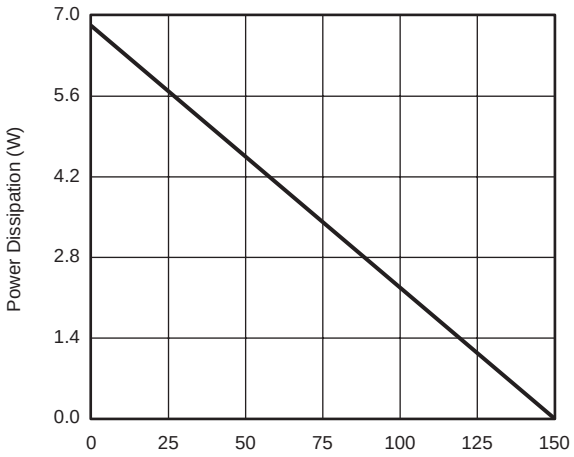
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

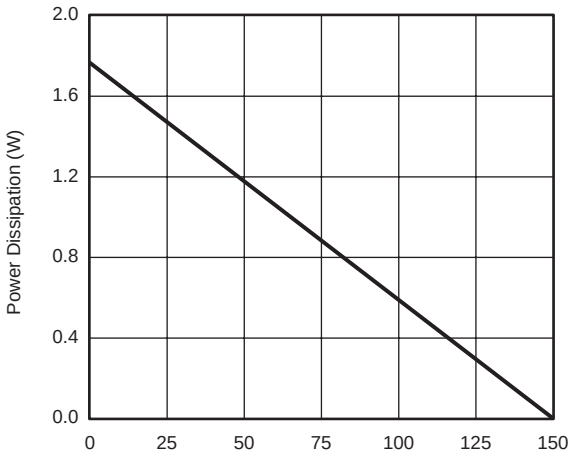
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



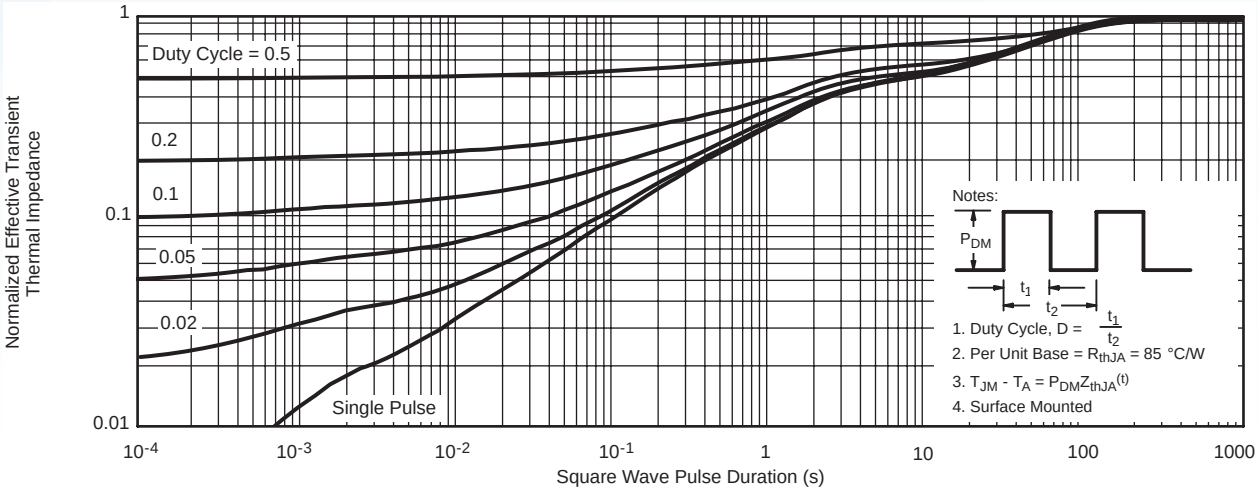
Power, Junction-to-Foot



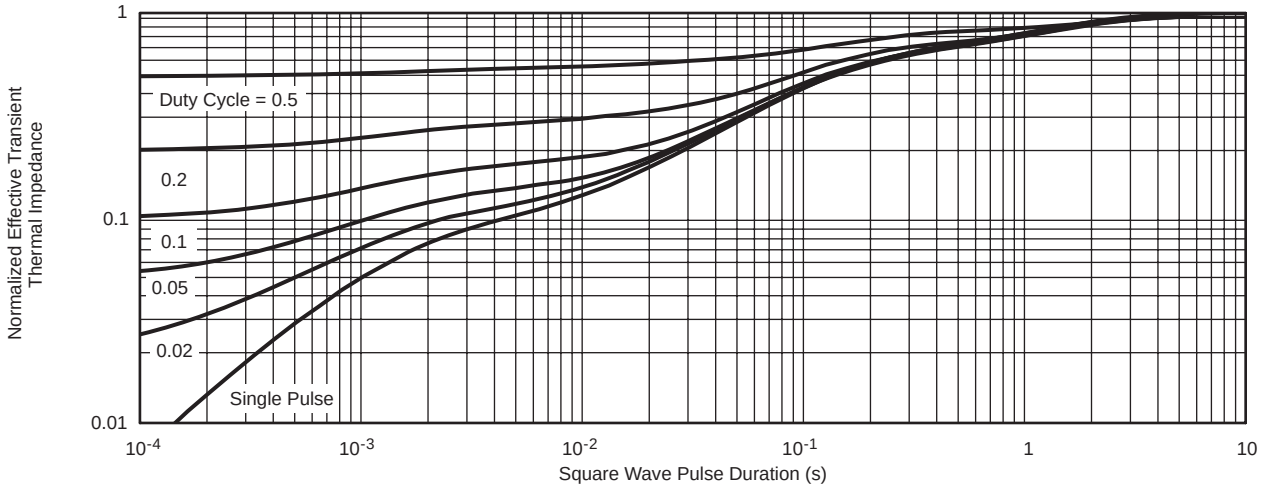
Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



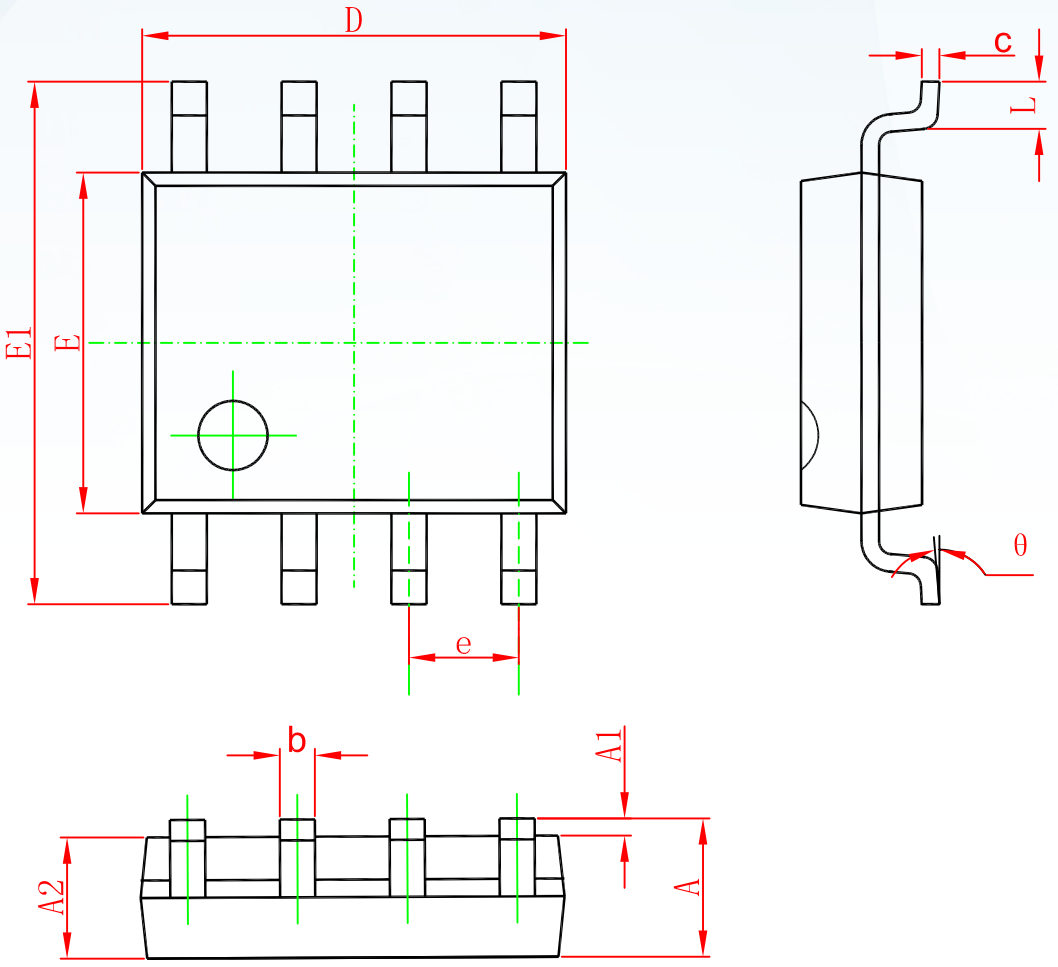
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

P-Channel 30 V (D-S) MOSFET

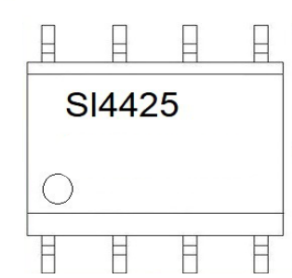
SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

P-Channel 30 V (D-S) MOSFET

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
SI4425DY	SOP-8	3000	Tape and reel

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